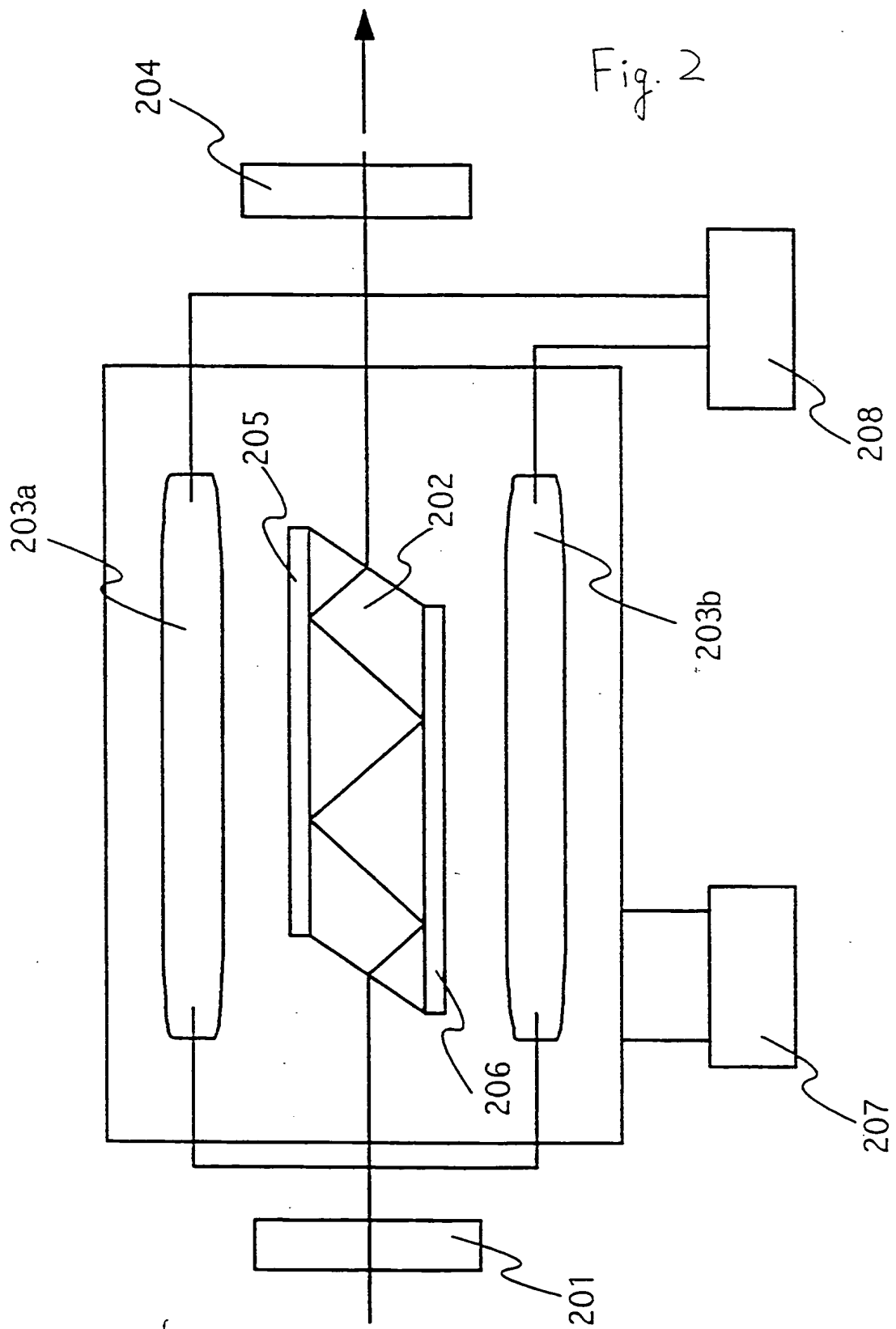
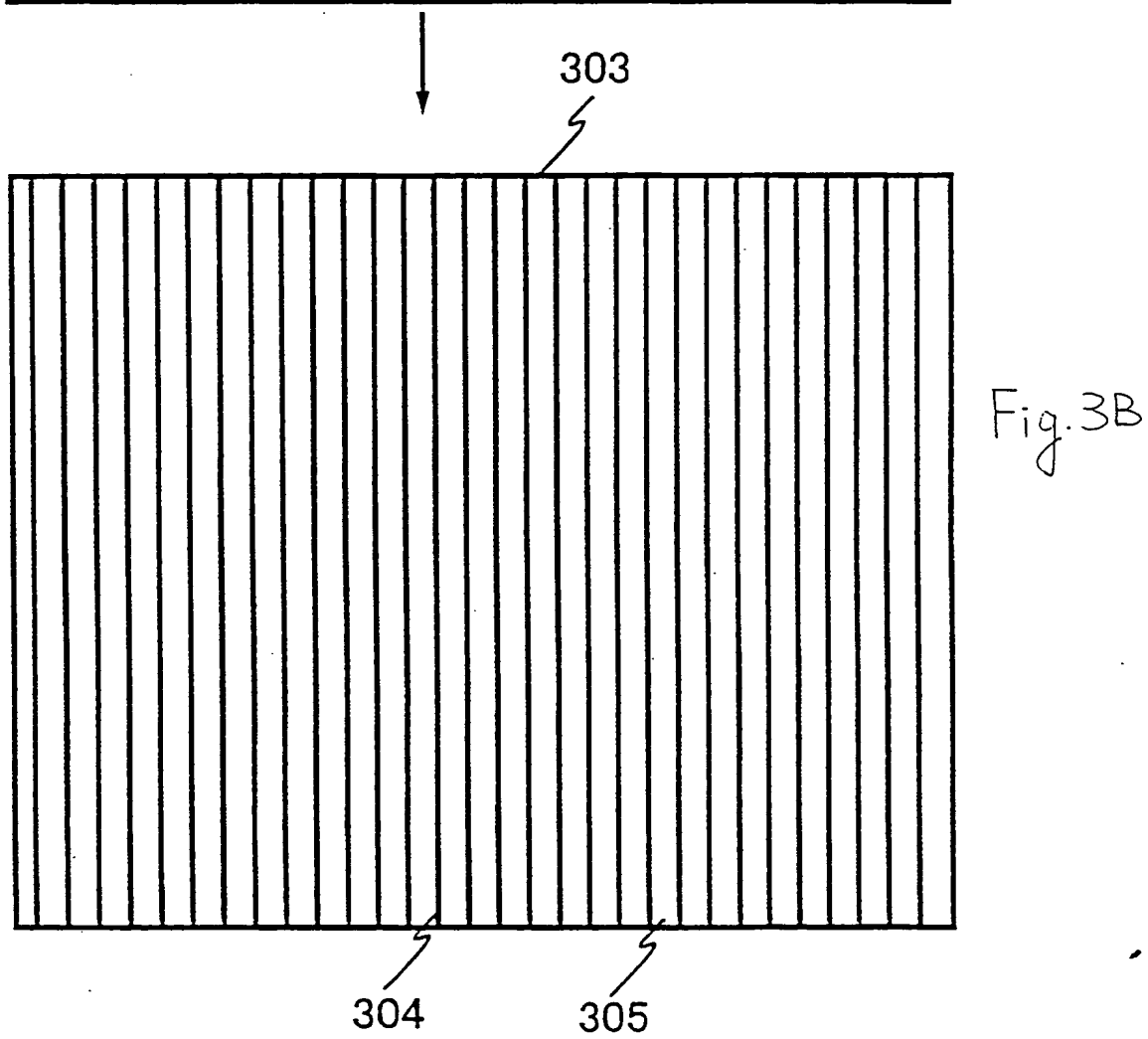
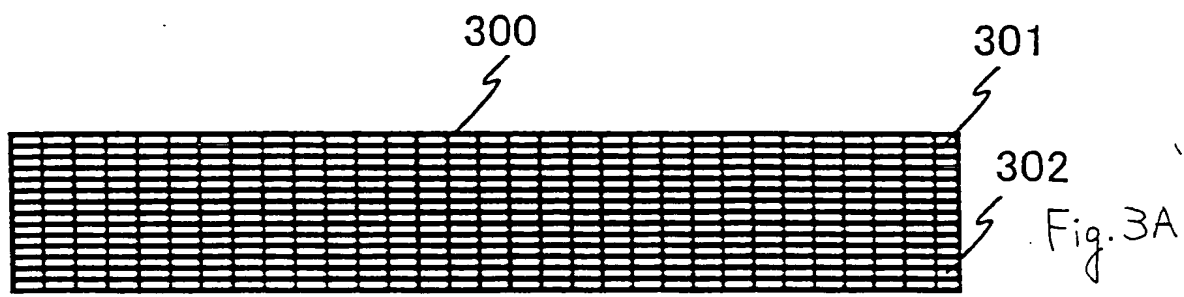
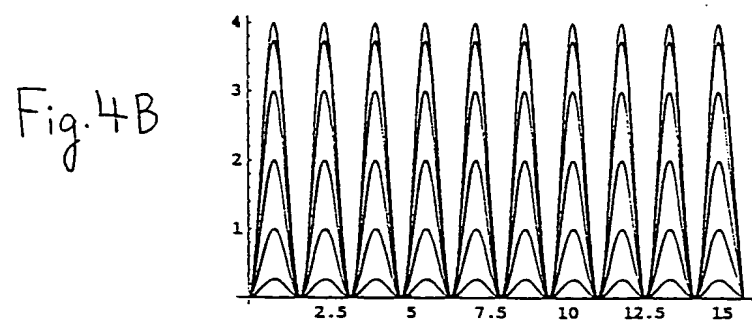
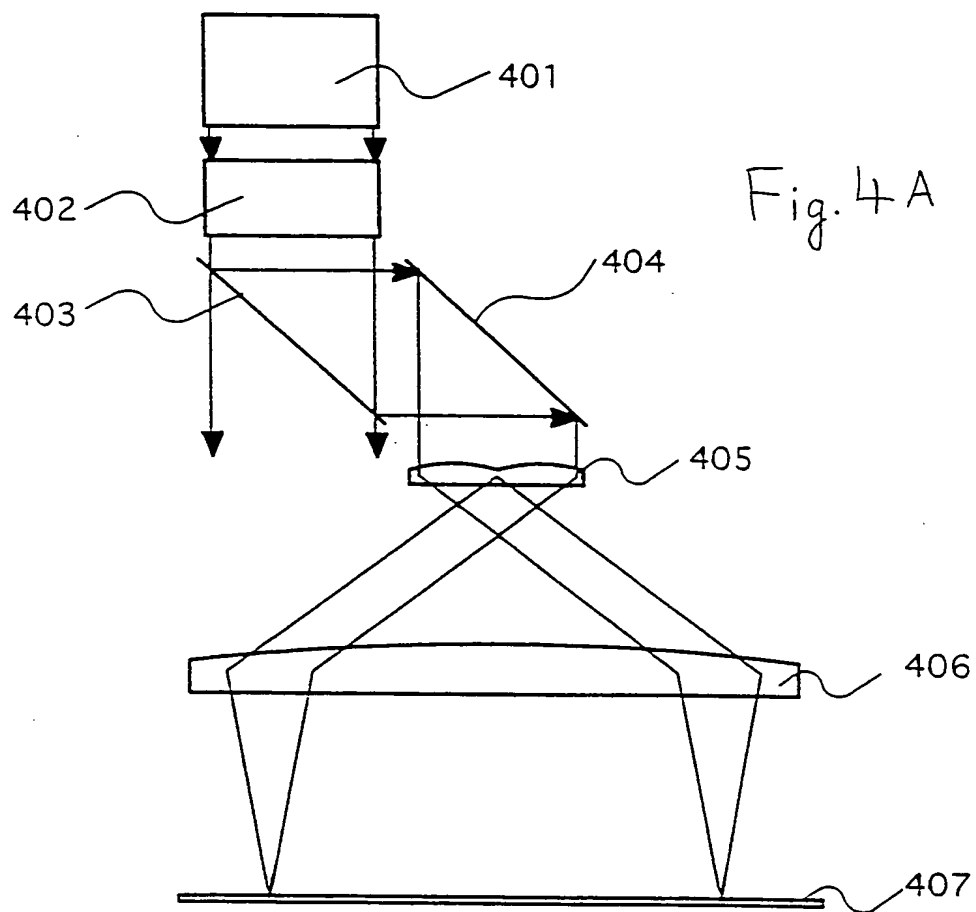


Fig. 1







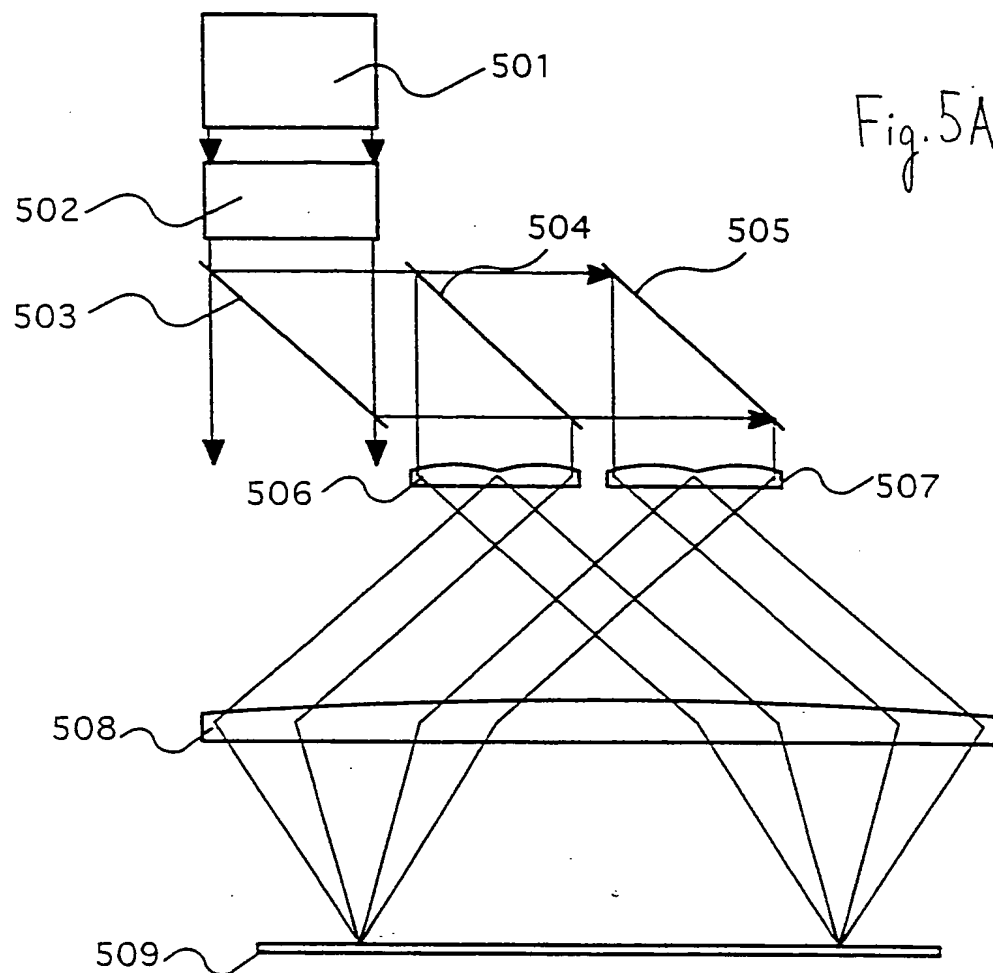
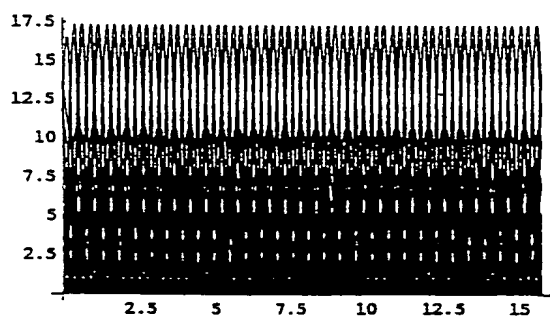


Fig. 5B



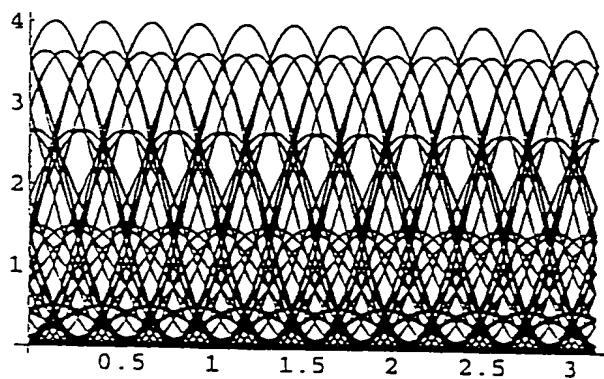


Fig. 6

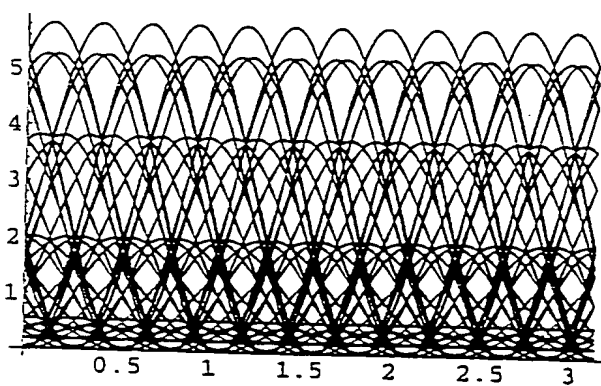


Fig. 7

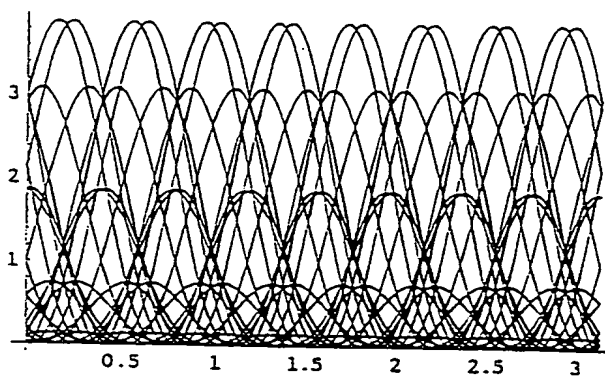


Fig. 8

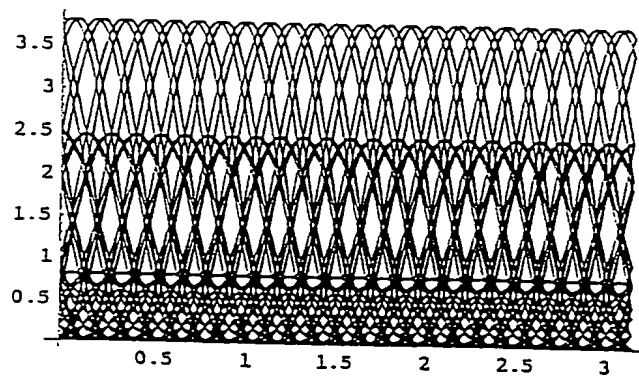


Fig. 9

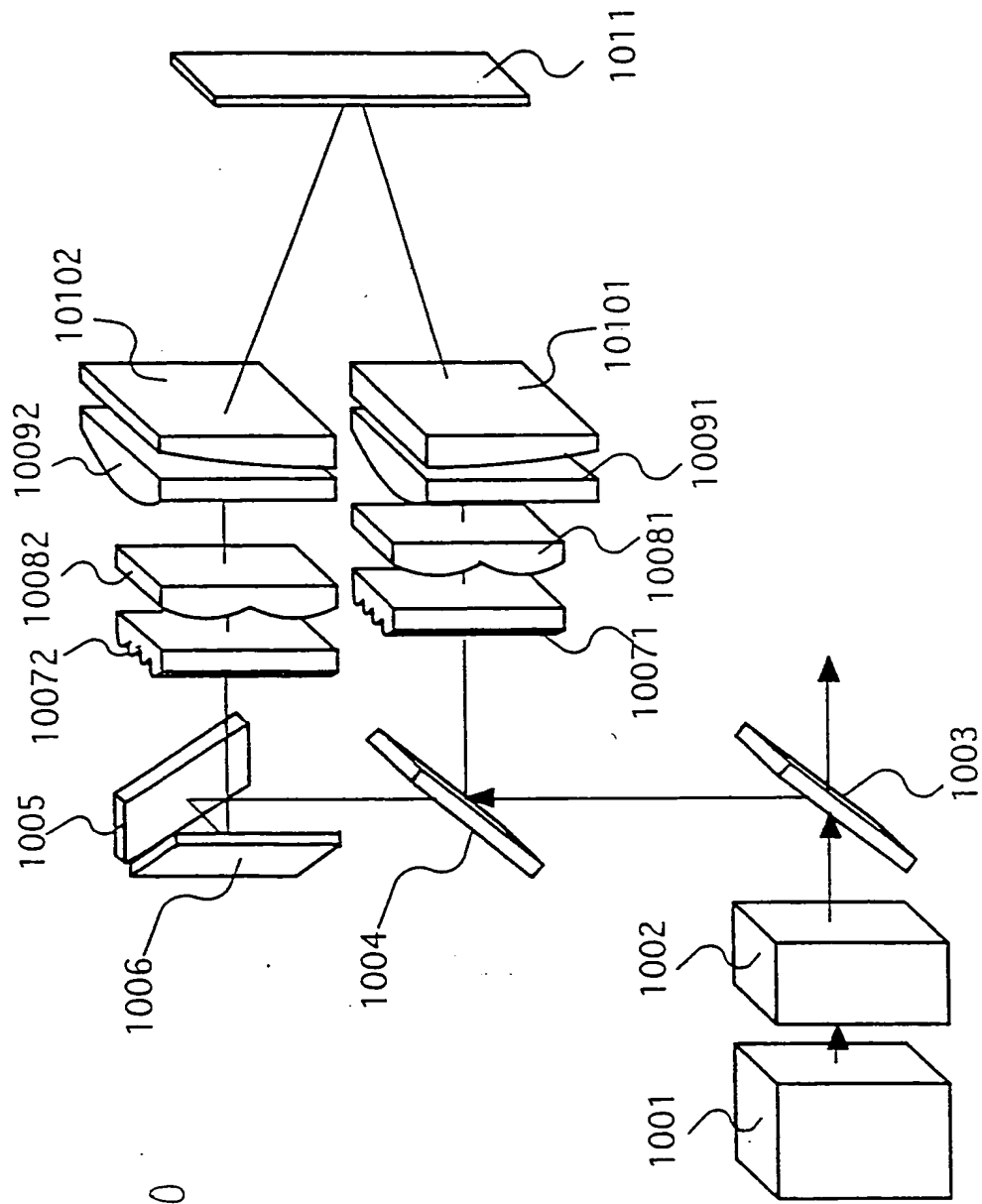


Fig. 10

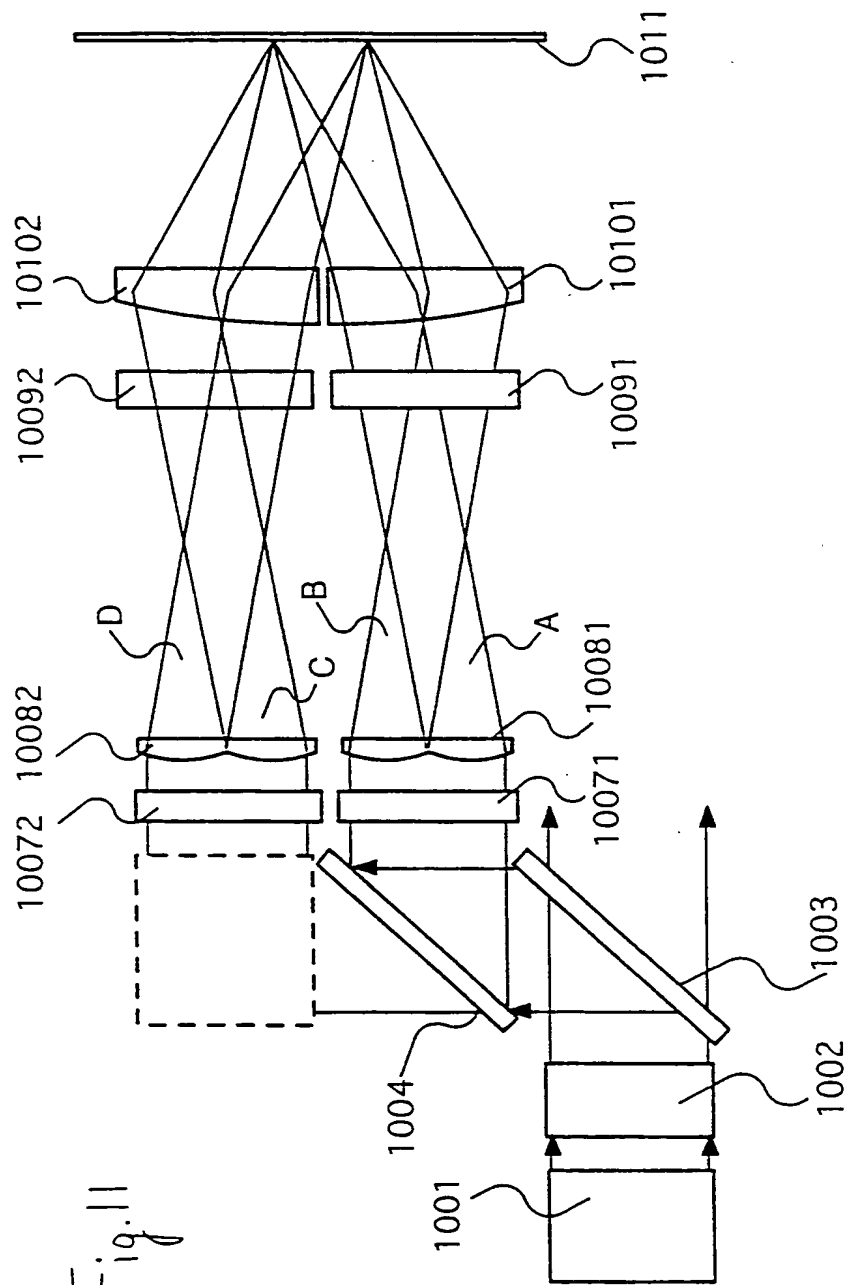


Fig. II

Fig. 12A

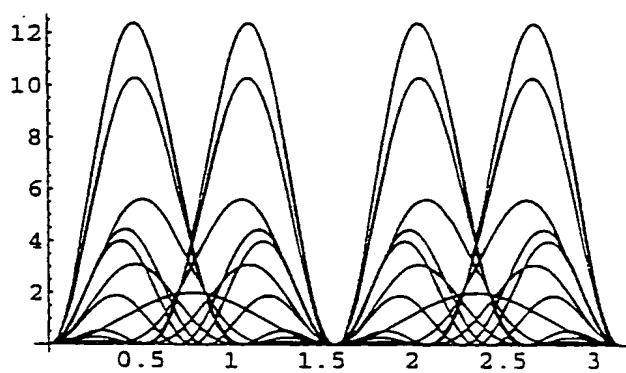
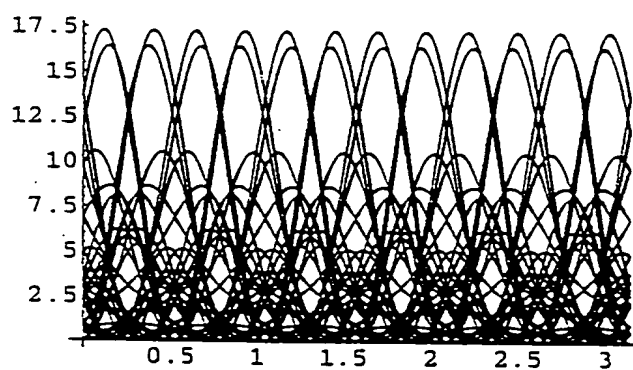


Fig. 12B



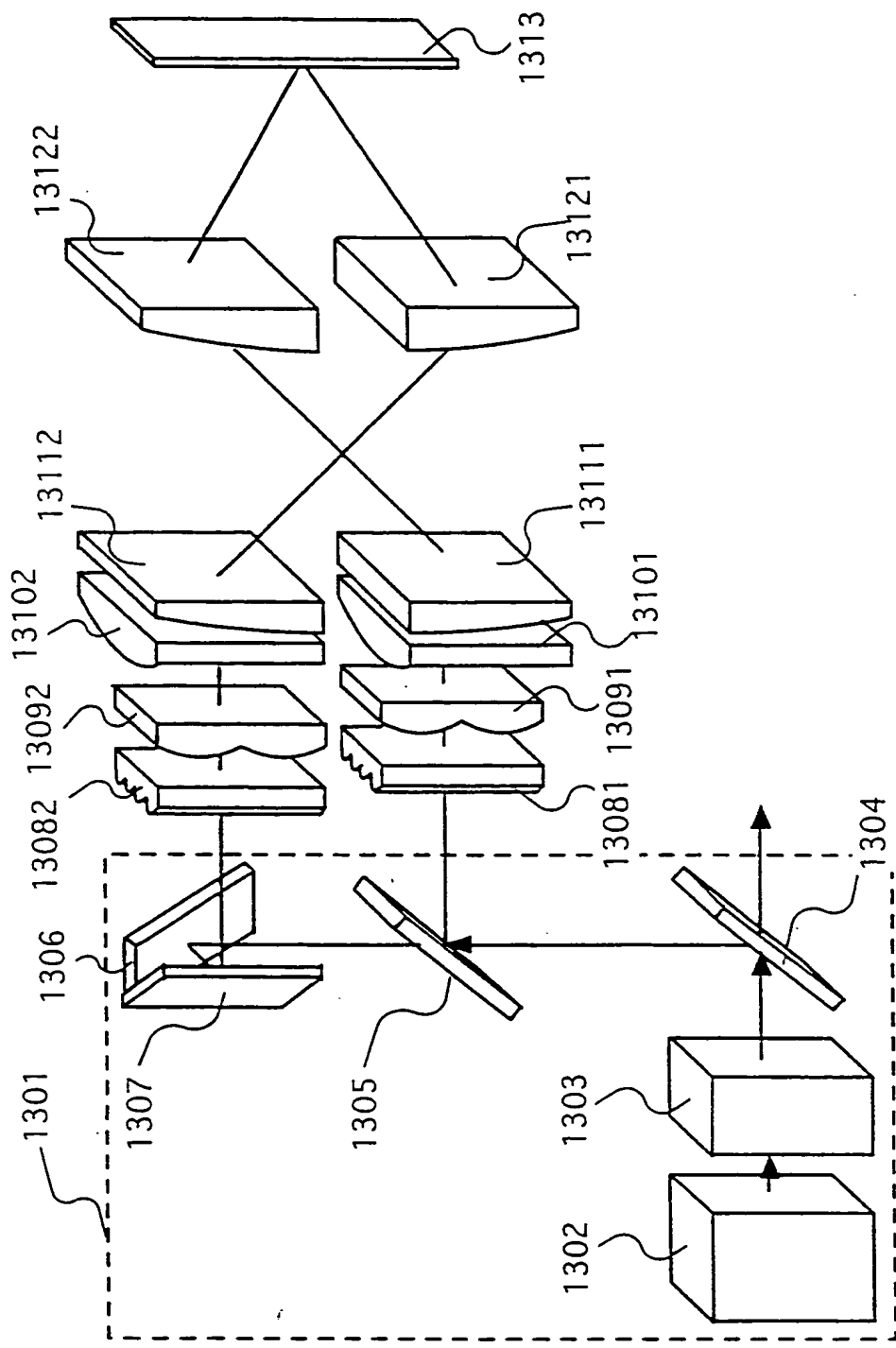
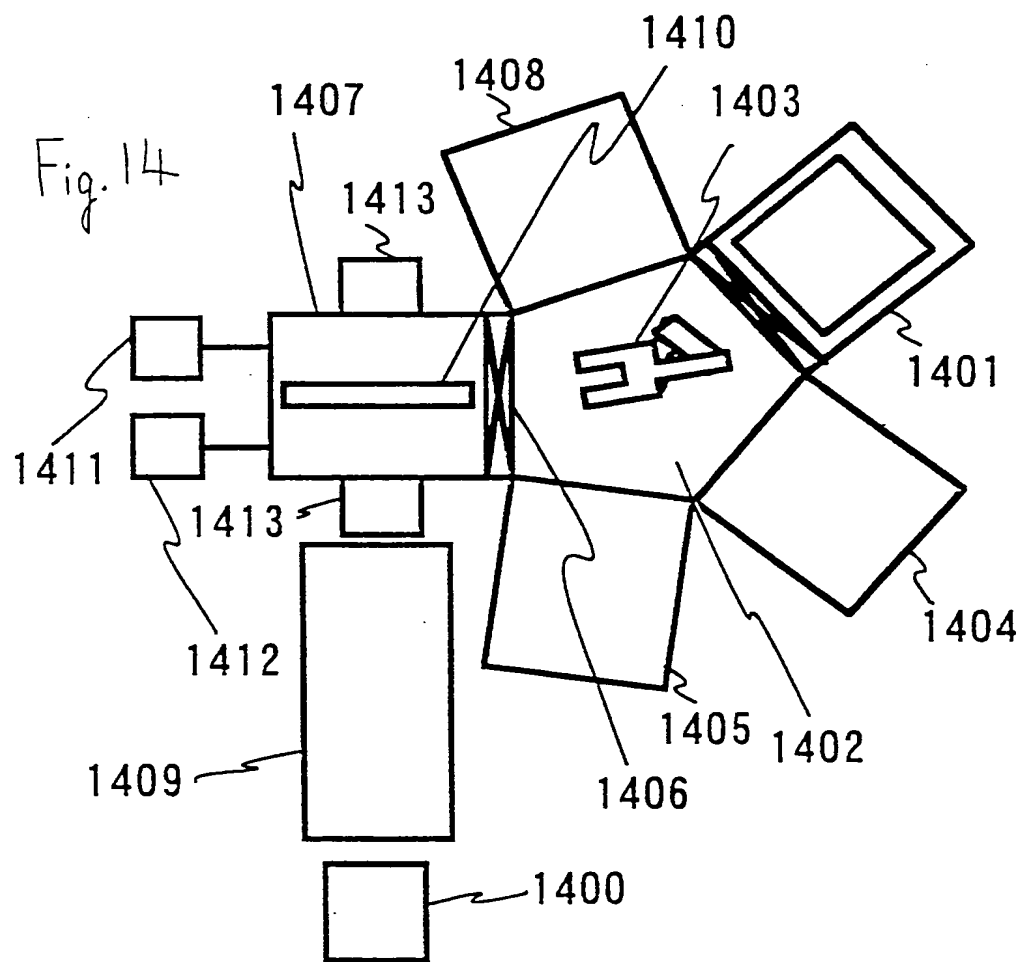
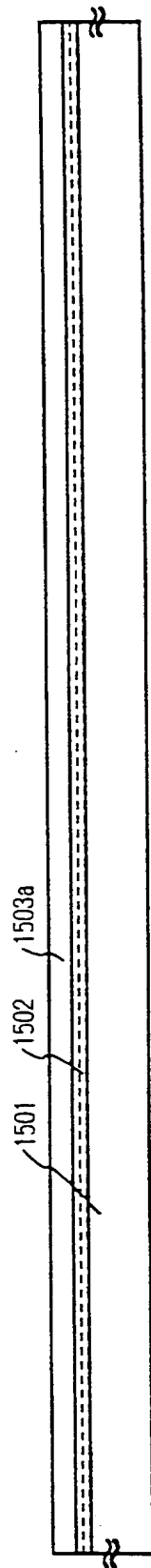
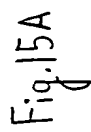


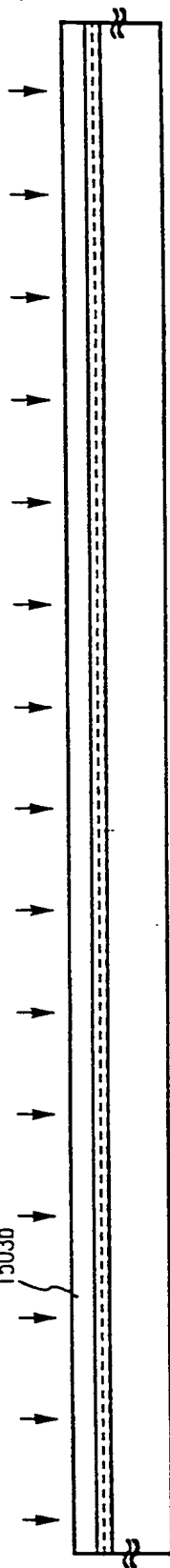
Fig. 13



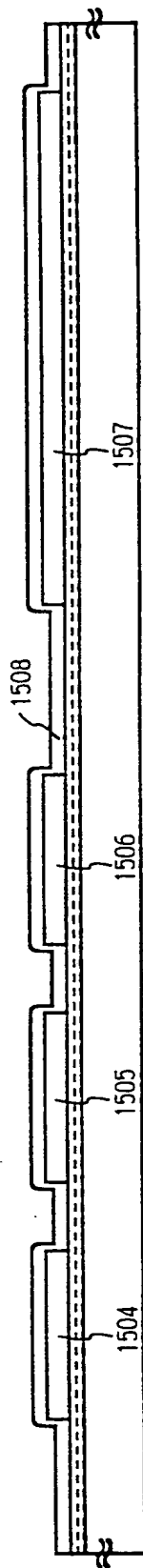
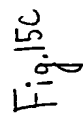
STEP OF FORMING AMORPHOUS SEMICONDUCTOR FILM



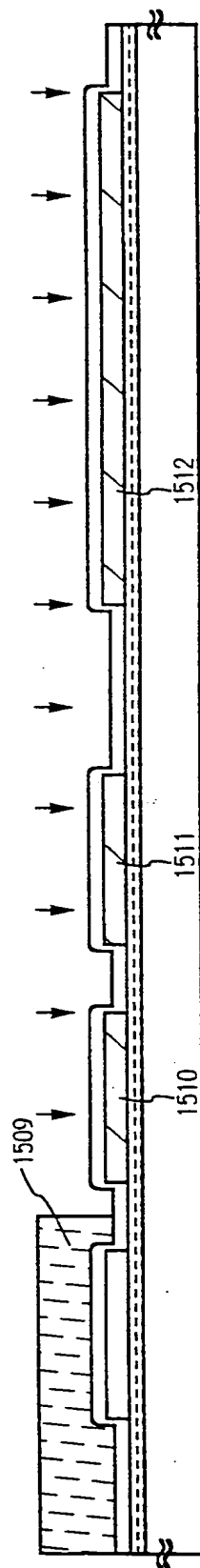
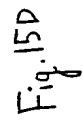
F_{19.15B} CRYSTALLIZATION STEP 1503b

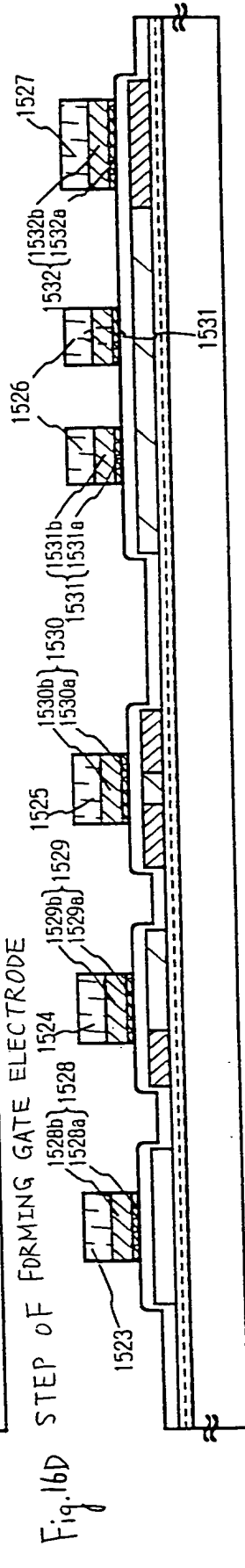
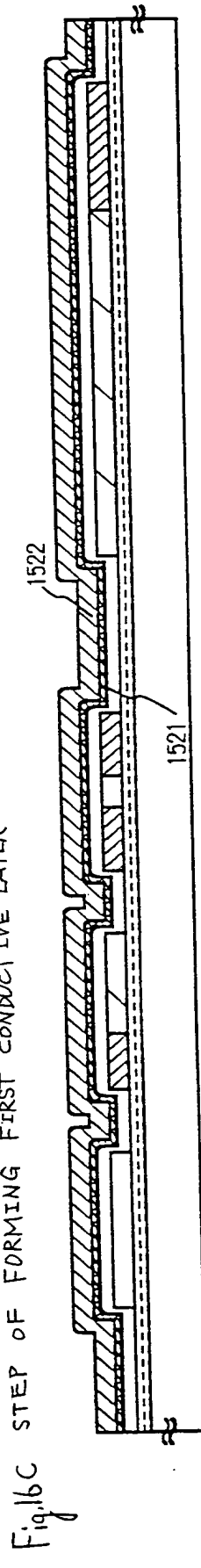
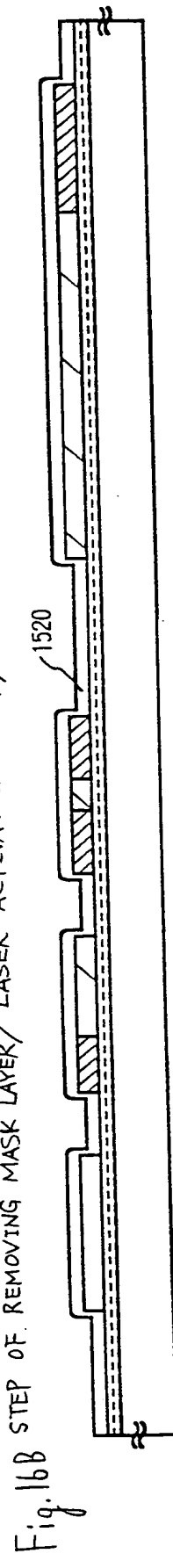
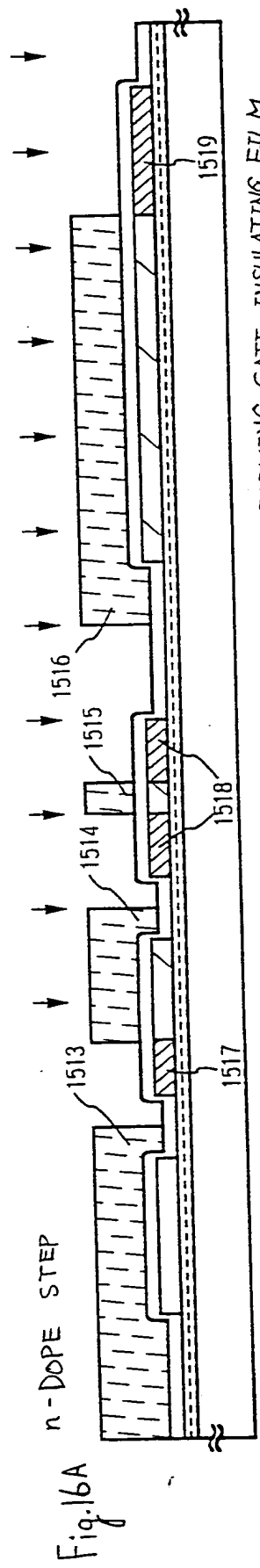


STEP OF FORMING MASK LAYER



E: 15D CHANNEL DOPE STEP





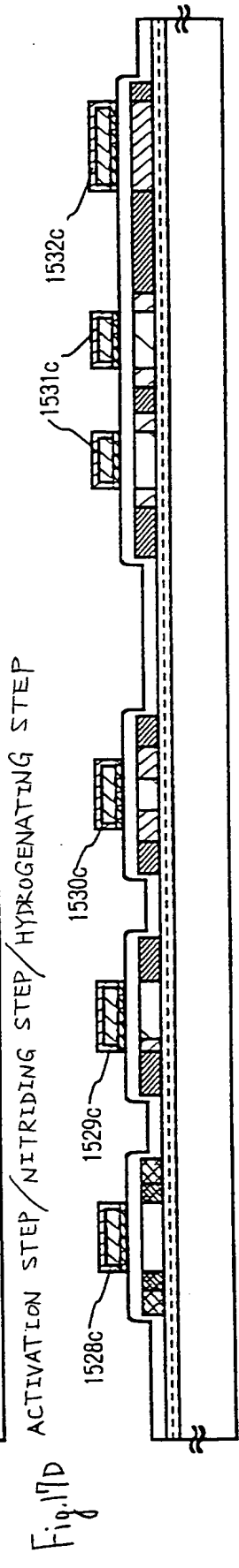
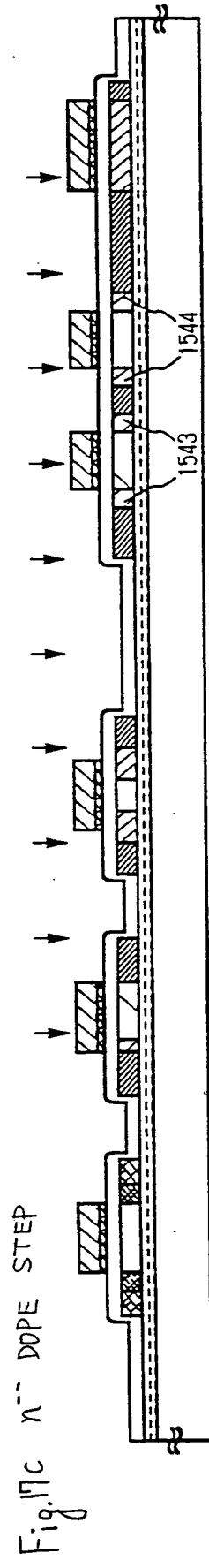
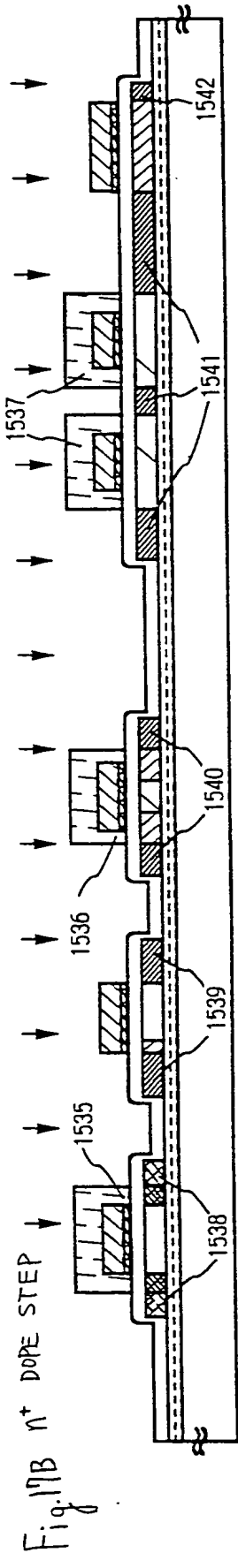
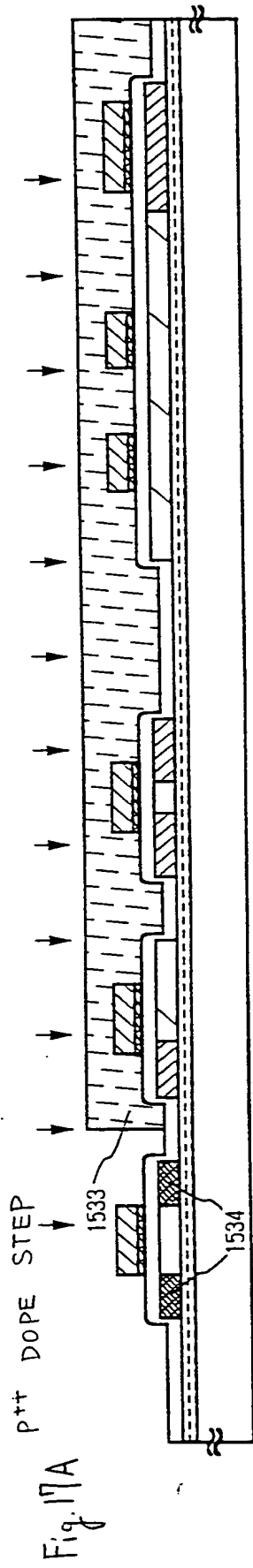


Fig. 18A STEP OF FORMING SECOND CONDUCTIVE FILM

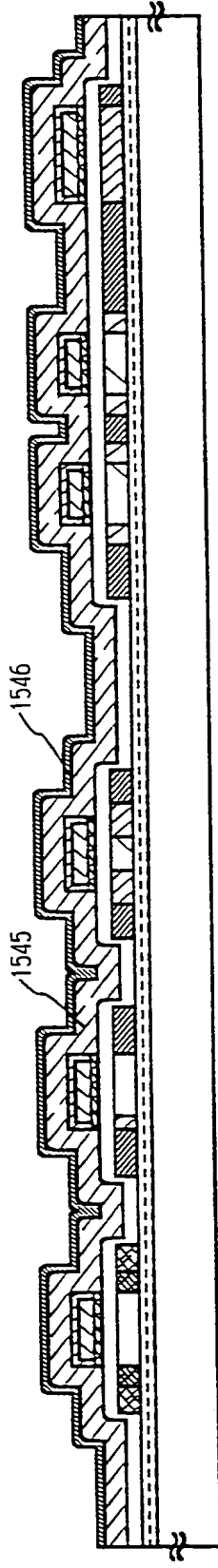


Fig. 18B FORMATION OF GATE WIRING

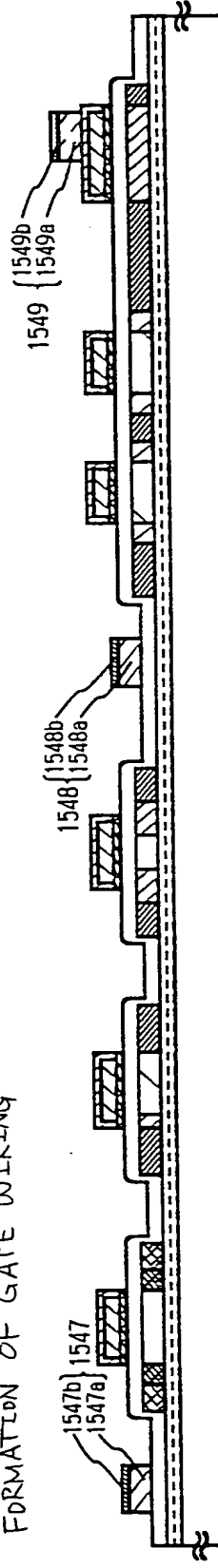


Fig. 18C STEP OF FORMING INTERLAYER INSULATING FILM / STEP OF FORMING CONTACT HOLE / STEP OF FORMING WIRING

Fig. 18C STEP OF FORMING PASSIVATION FILM

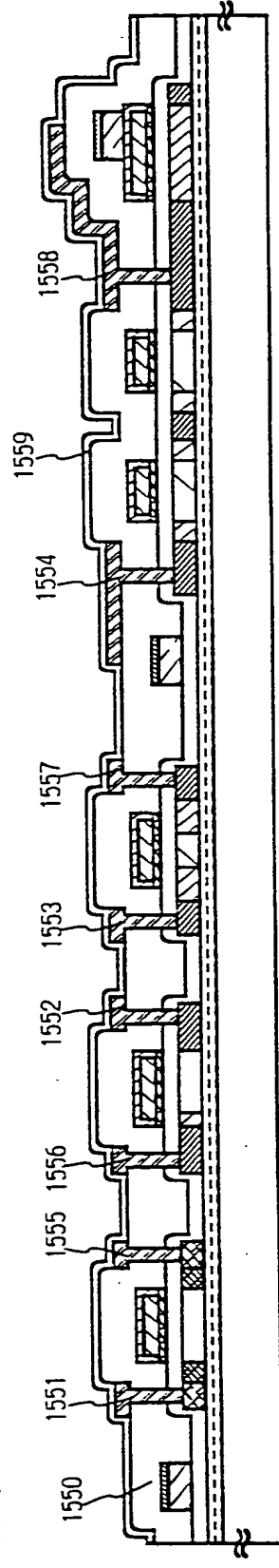
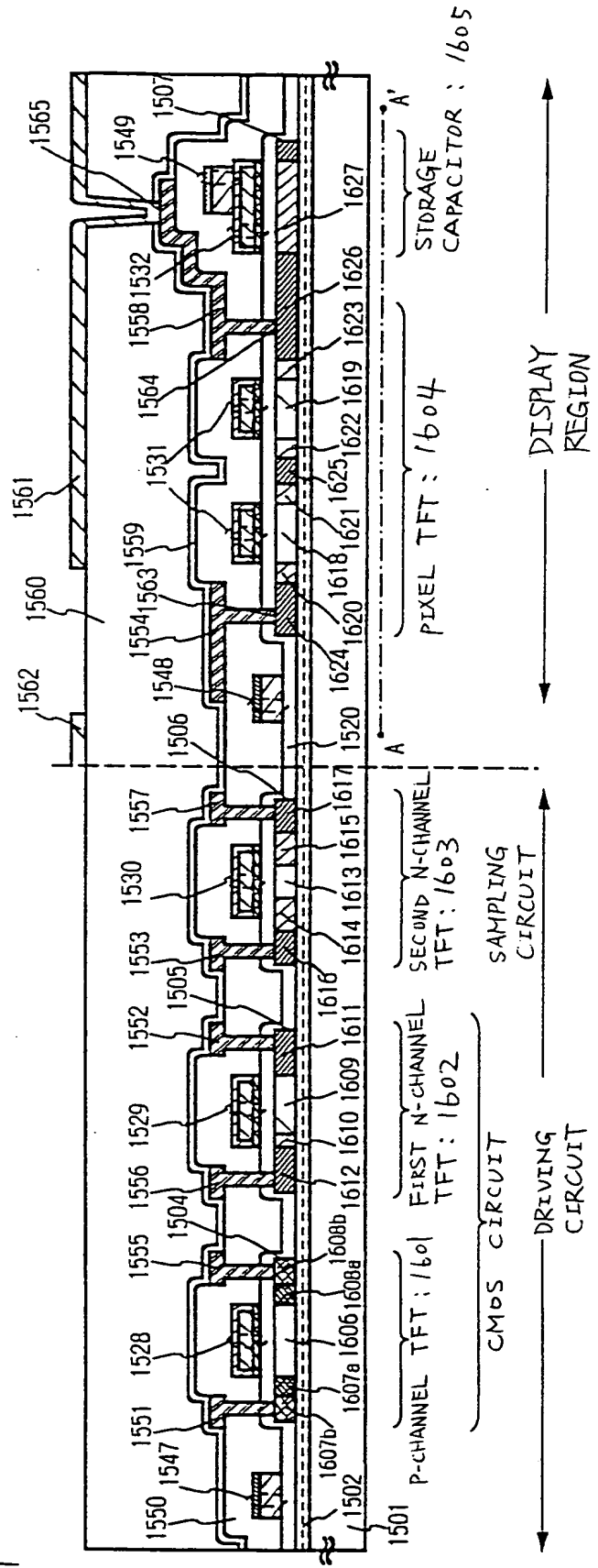


Fig. 19 STEP OF FORMING RESIN FILM / STEP OF FORMING CONTACT HOLE / STEP OF FORMING PIXEL ELECTRODE



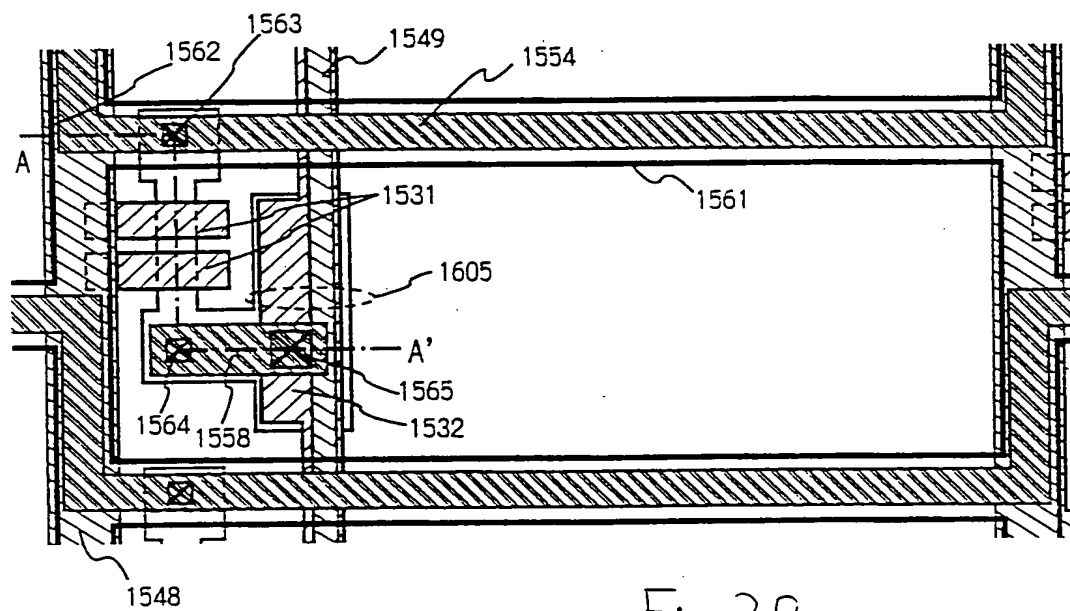


Fig. 20

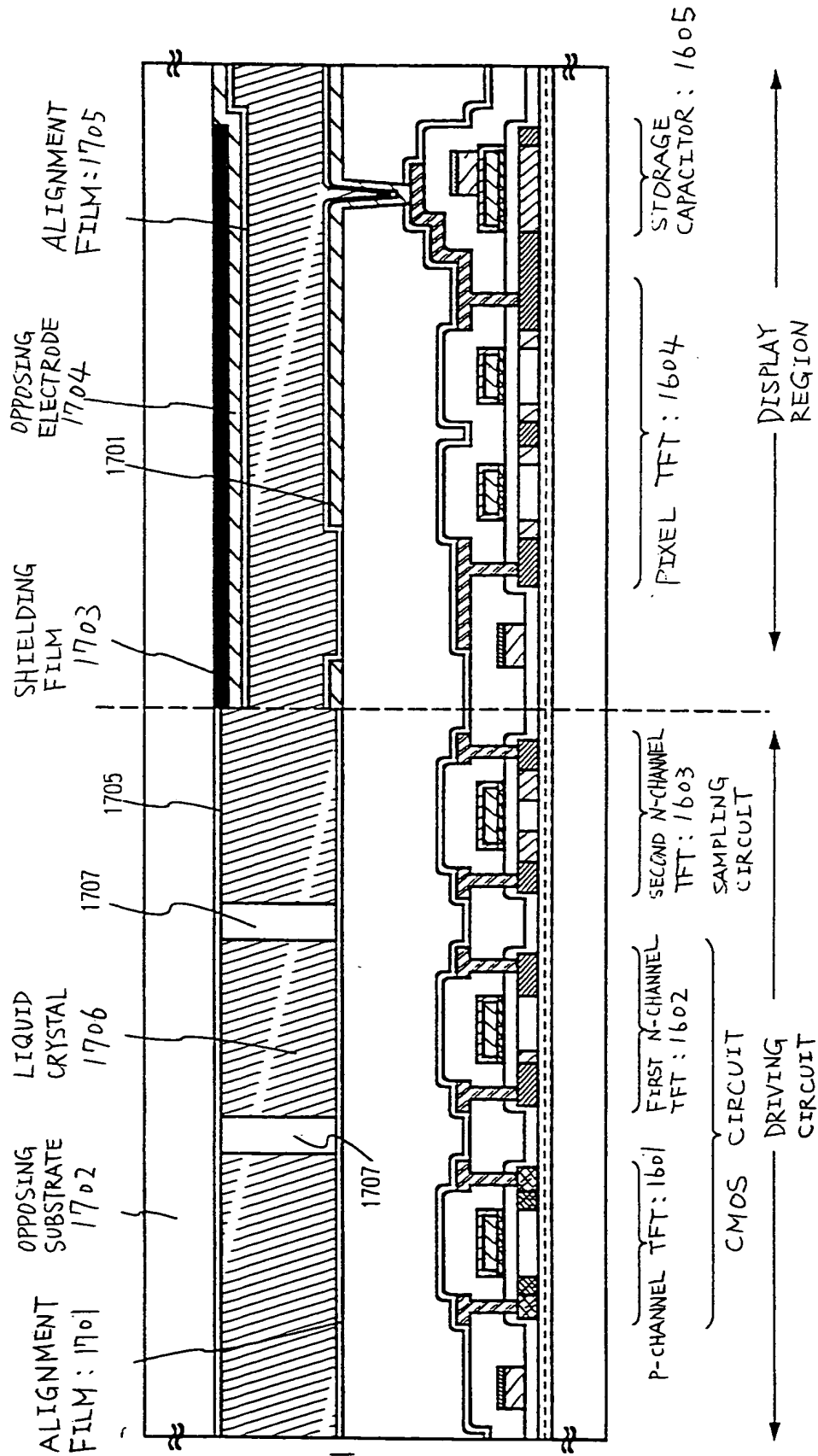


Fig. 21

Fig. 22A STEP OF FORMING AMORPHOUS SEMICONDUCTOR FILM

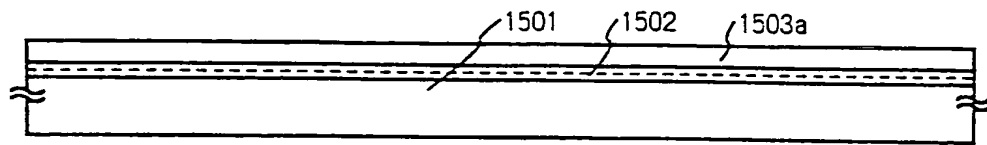


Fig. 22B STEP OF ADDING CATALYST ELEMENT 1801

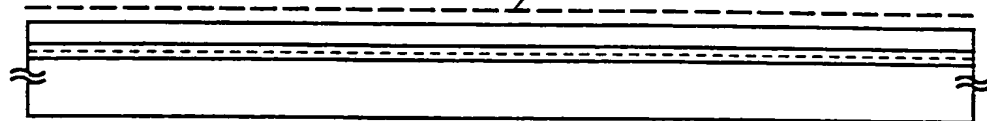


Fig. 22C LASER CRYSTALLIZATION STEP 1802

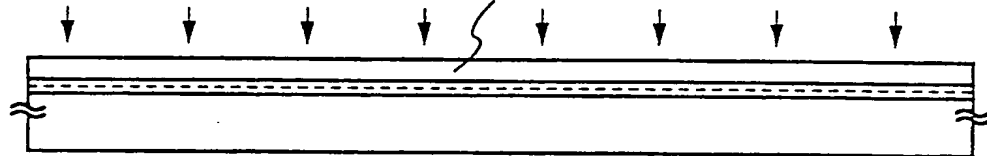


Fig. 23A STEP OF FORMING AMORPHOUS SEMICONDUCTOR FILM

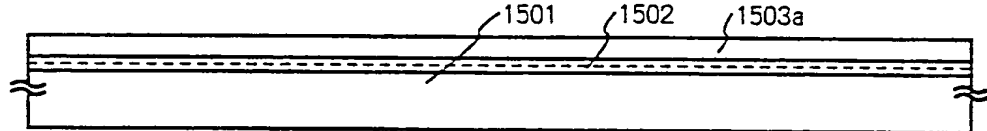


Fig. 23B STEP OF ADDING CATALYST ELEMENT 1901

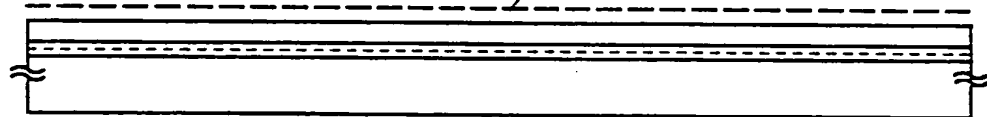
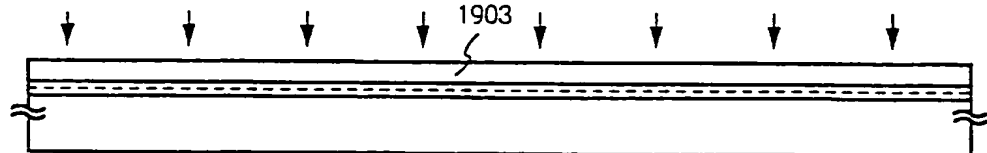


Fig. 23C CRYSTALLIZATION STEP (THERMAL CRYSTALLIZATION) 1902



Fig. 23D LASER ANNEAL STEP 1903



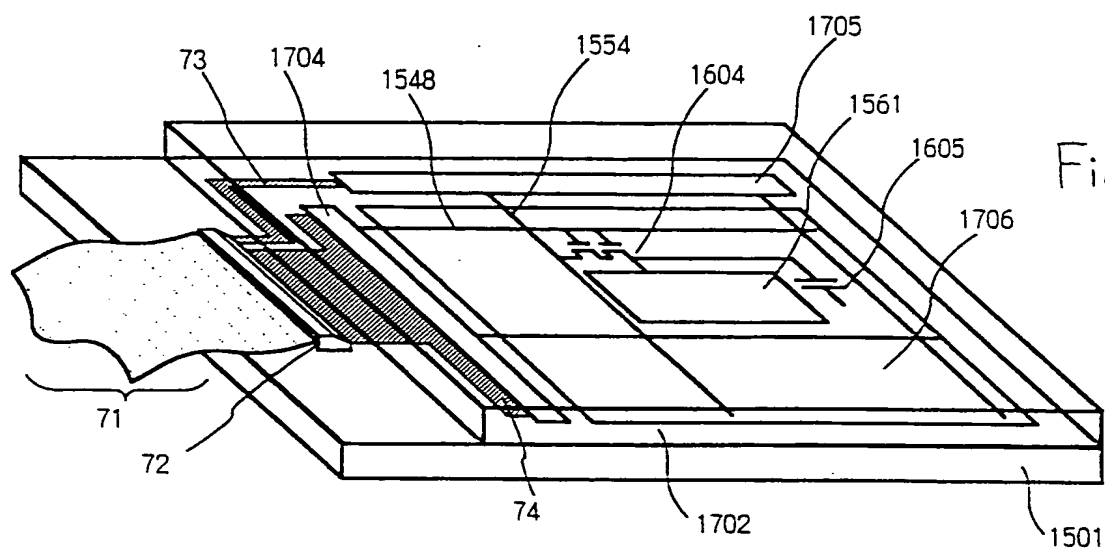


Fig. 24

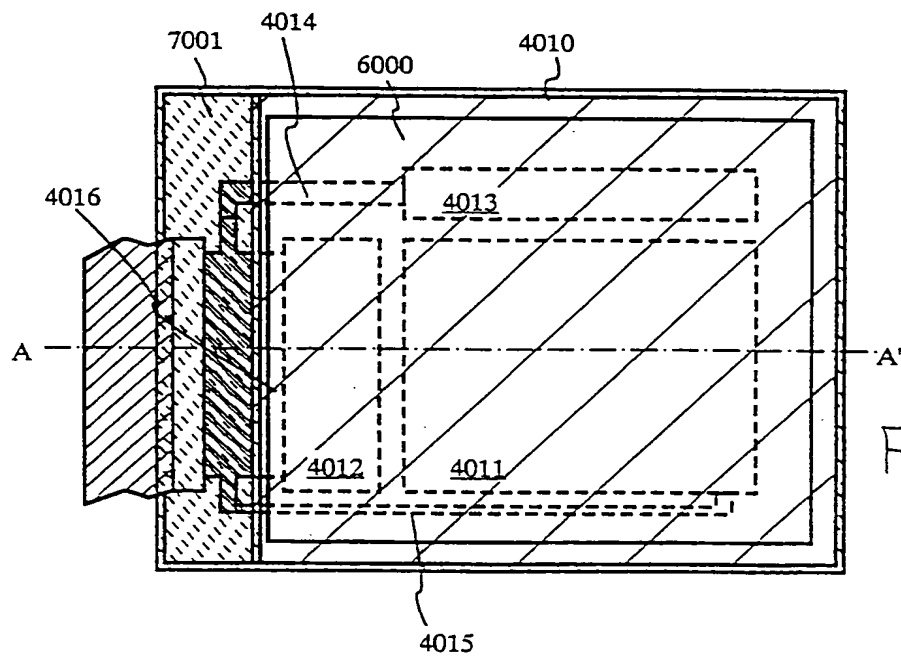


Fig. 25A

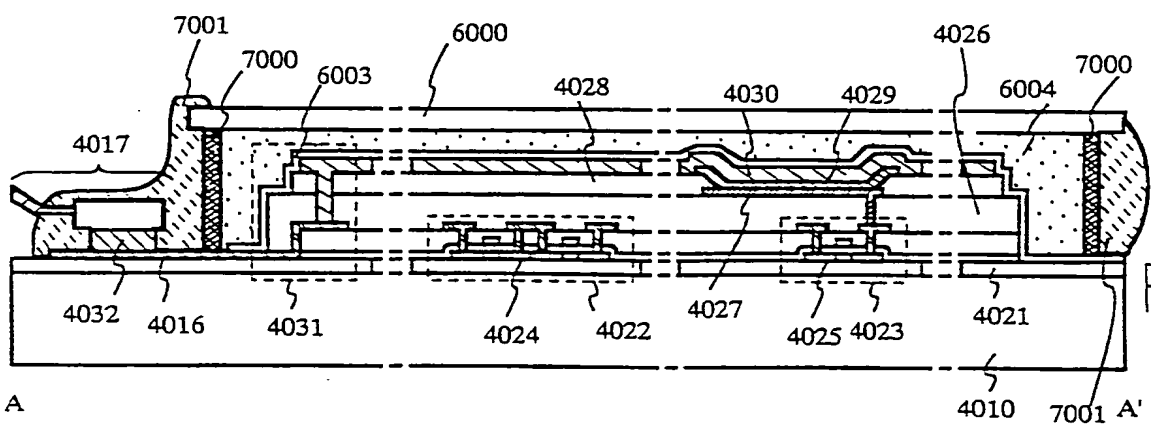
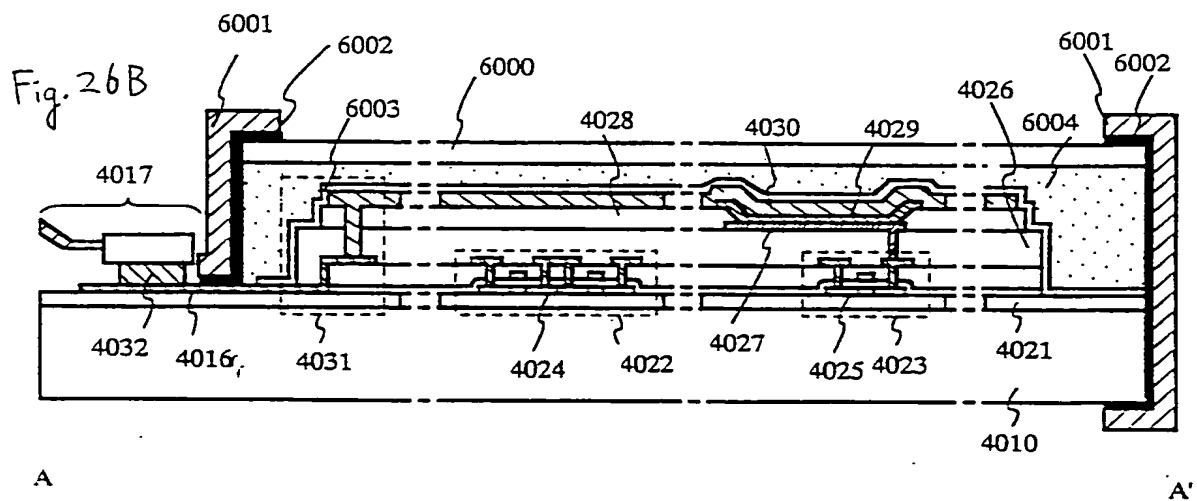
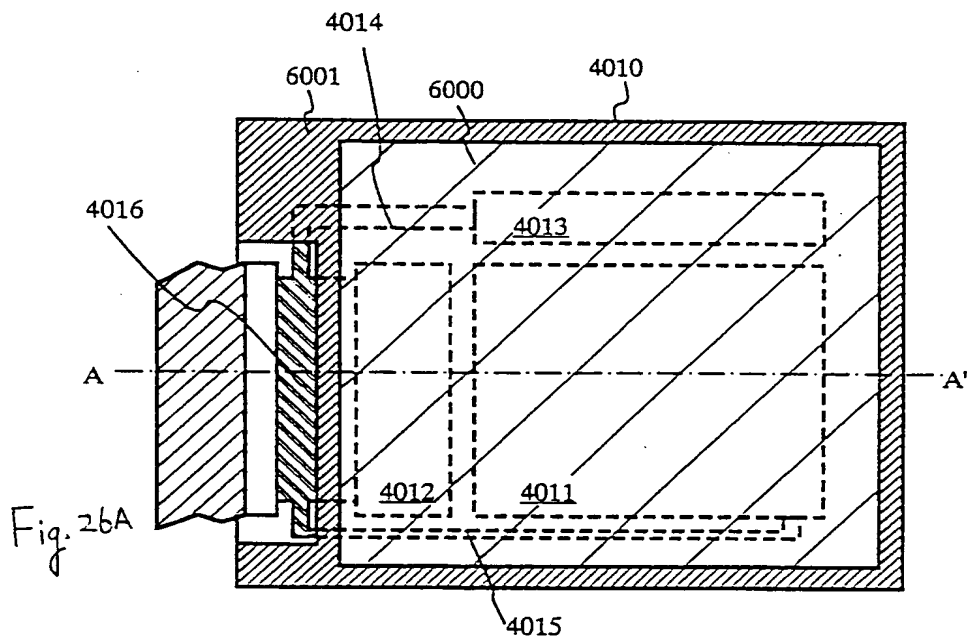


Fig. 25B



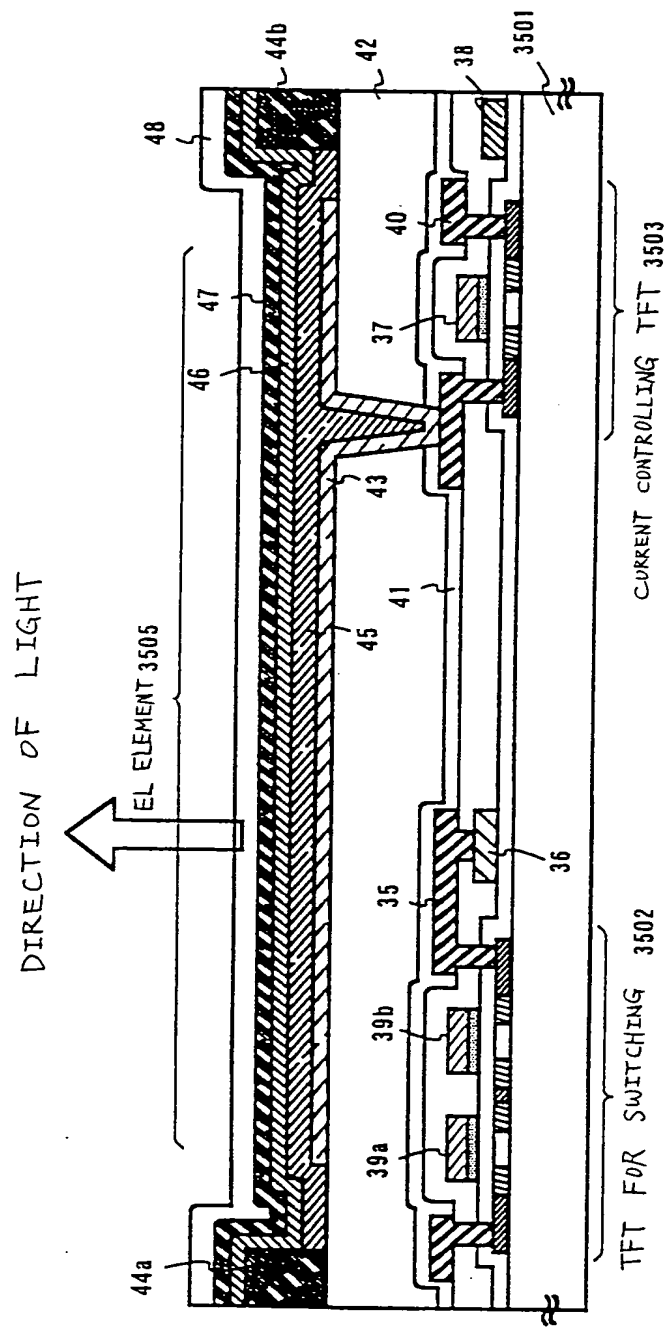


Fig. 27

Fig. 28A

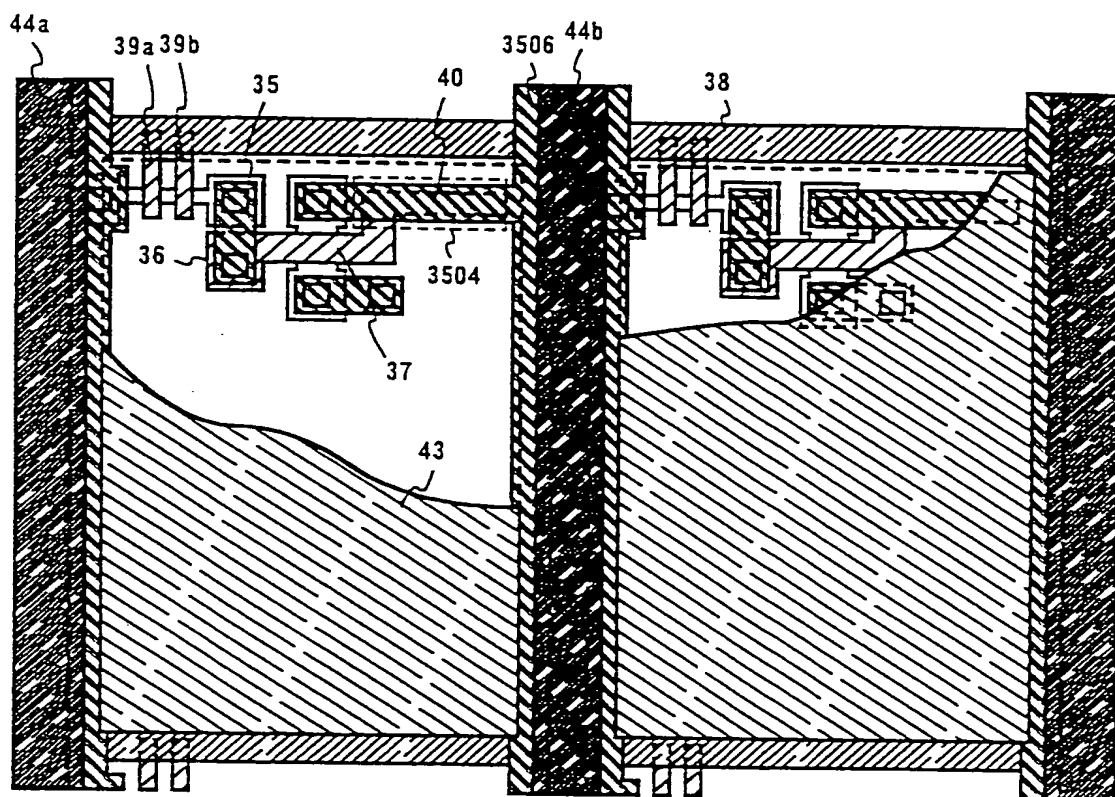
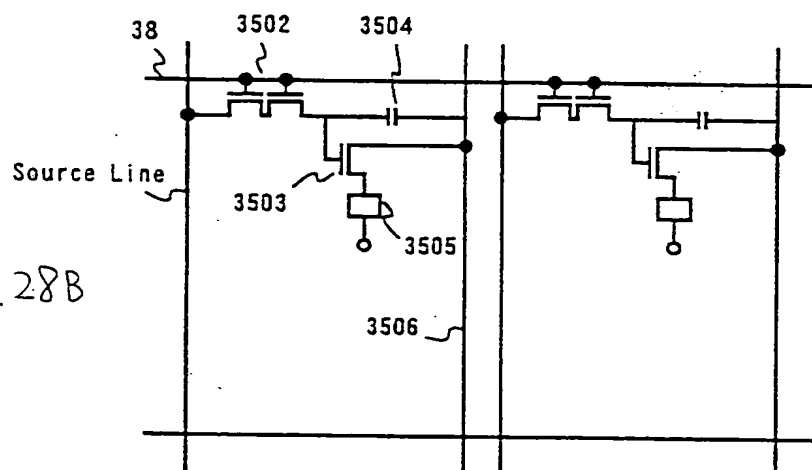


Fig. 28B



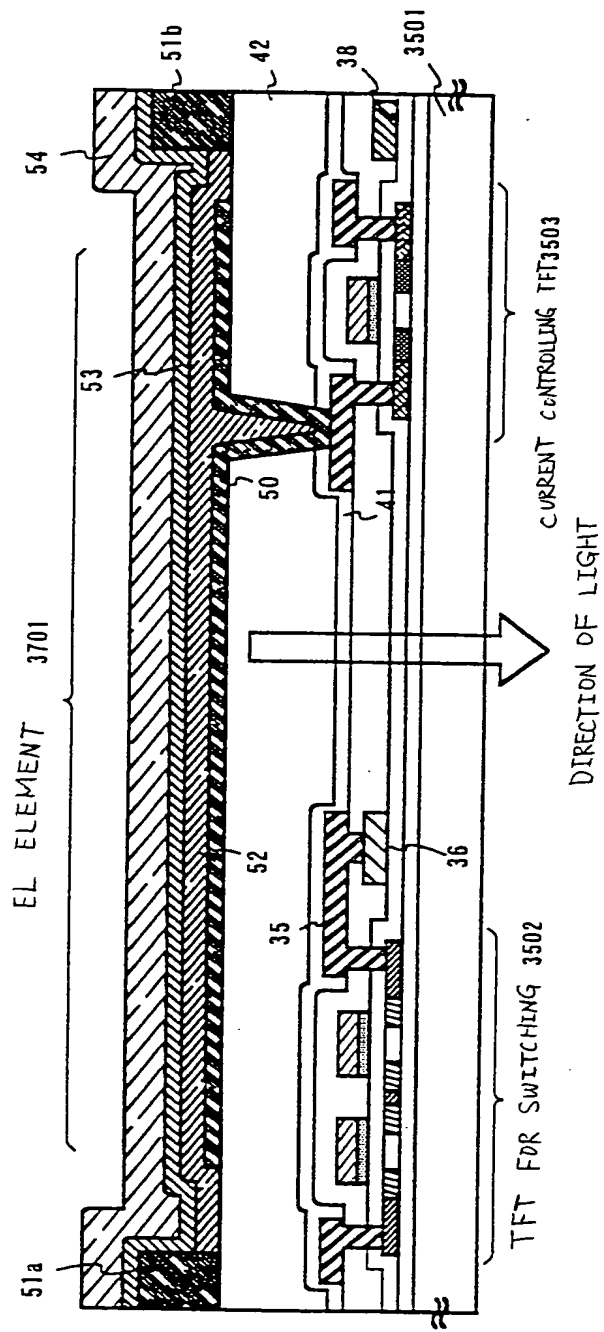


Fig. 29

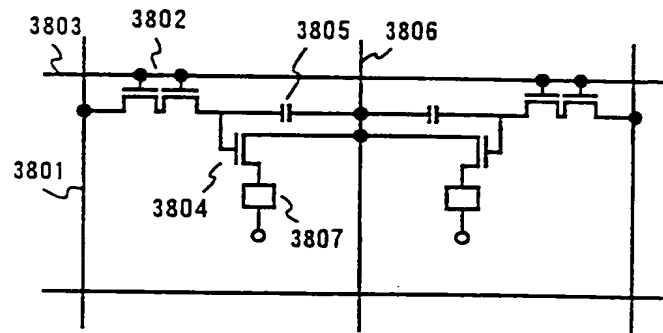


Fig. 30(A)

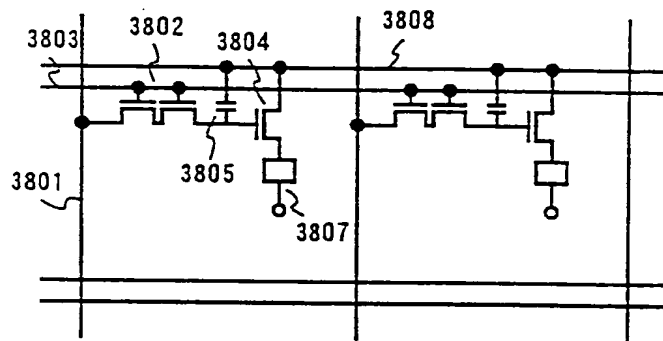


Fig. 30(B)

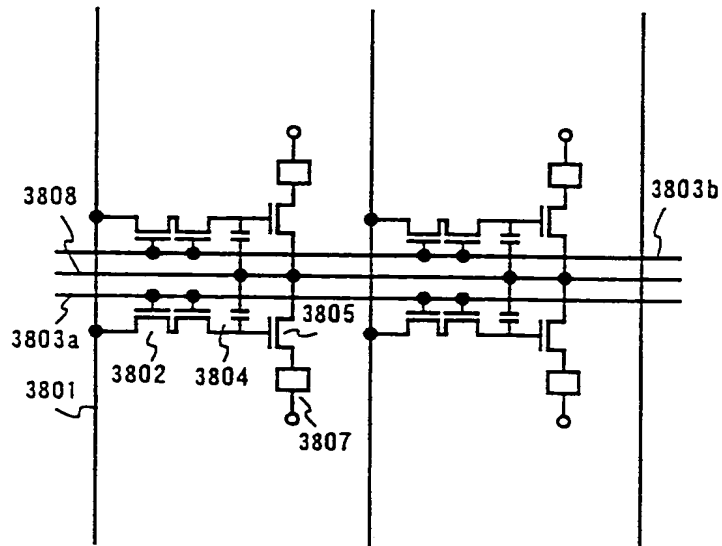
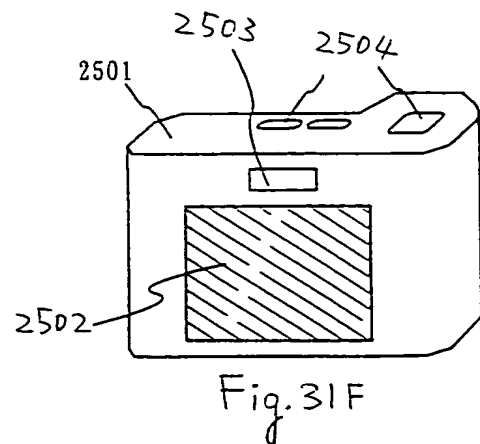
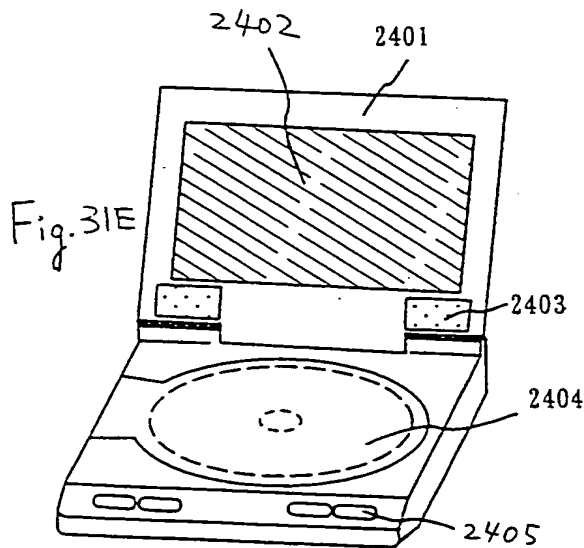
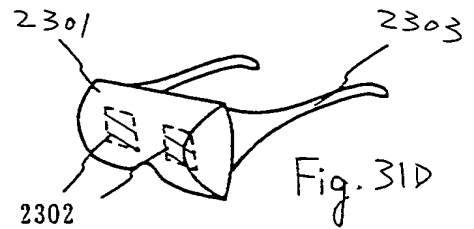
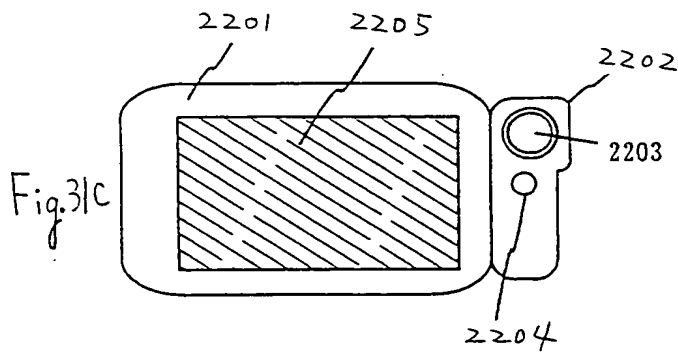
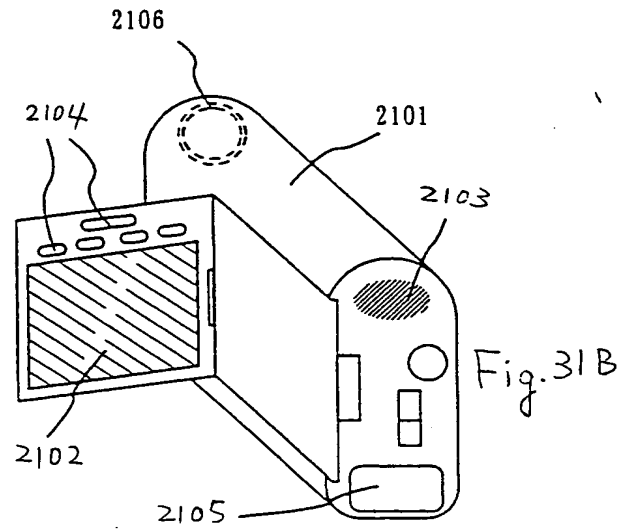
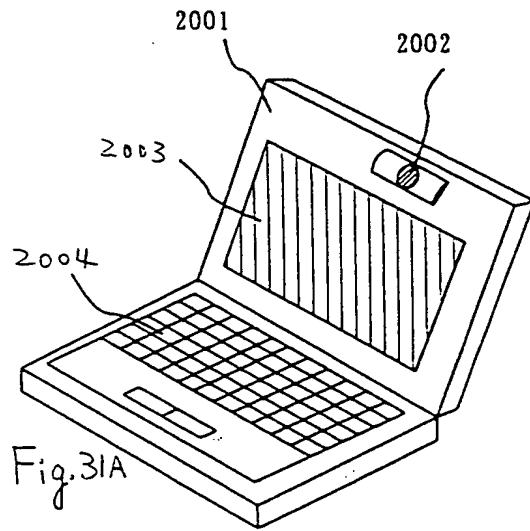


Fig. 30(c)



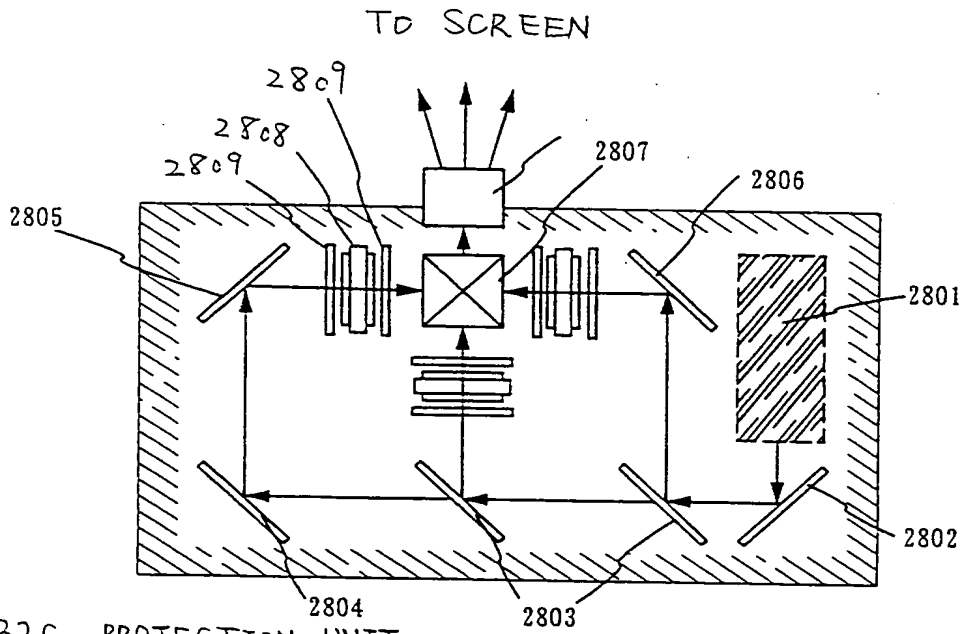
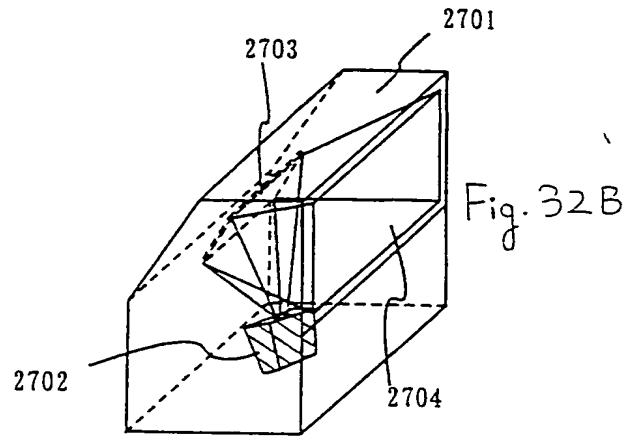
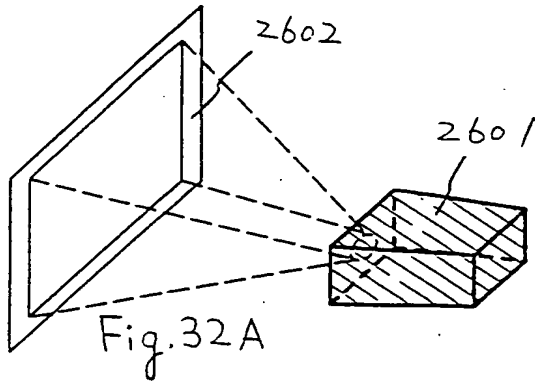


Fig. 32C PROJECTION UNIT
(THREE PLATE SYSTEM)

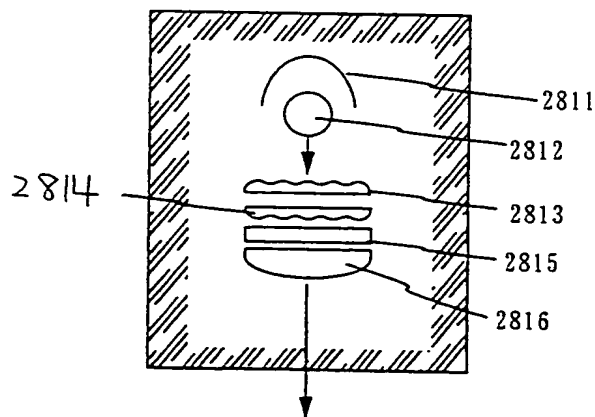


Fig. 32D
LIGHT SOURCE OPTICAL SYSTEM

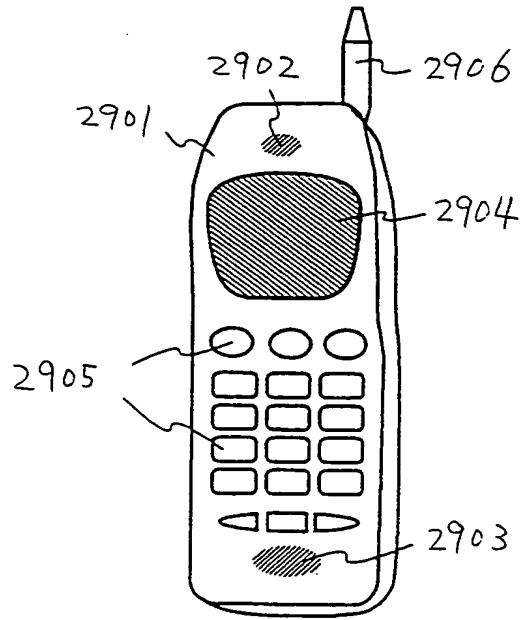


Fig. 33A

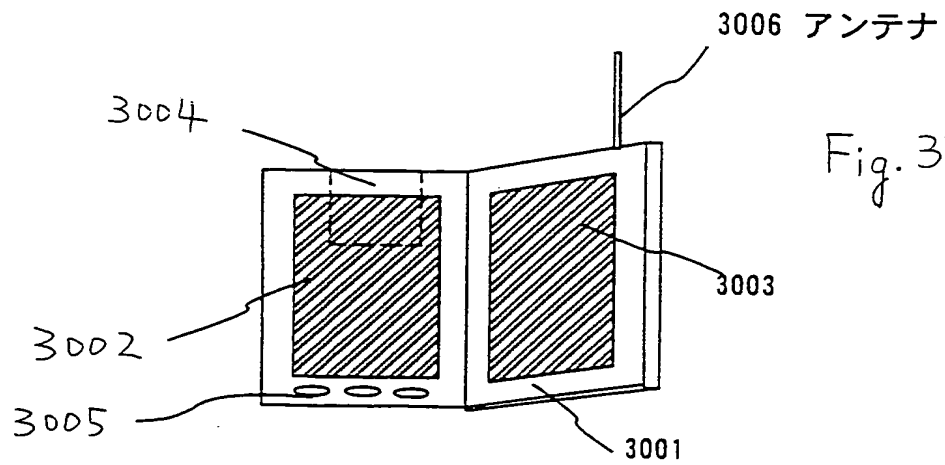


Fig. 33B

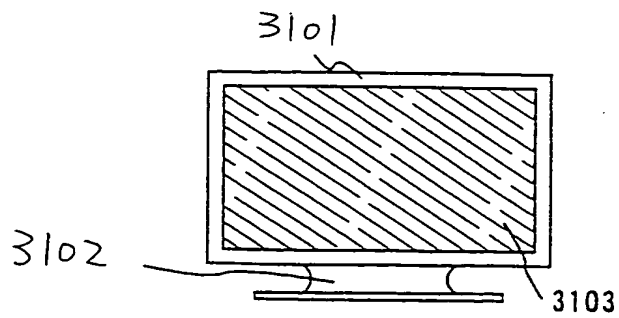


Fig. 33C

ABSORPTION RATIO TO 55 nm - THICK NON-SINGLE CRYSTAL SILICON FILM

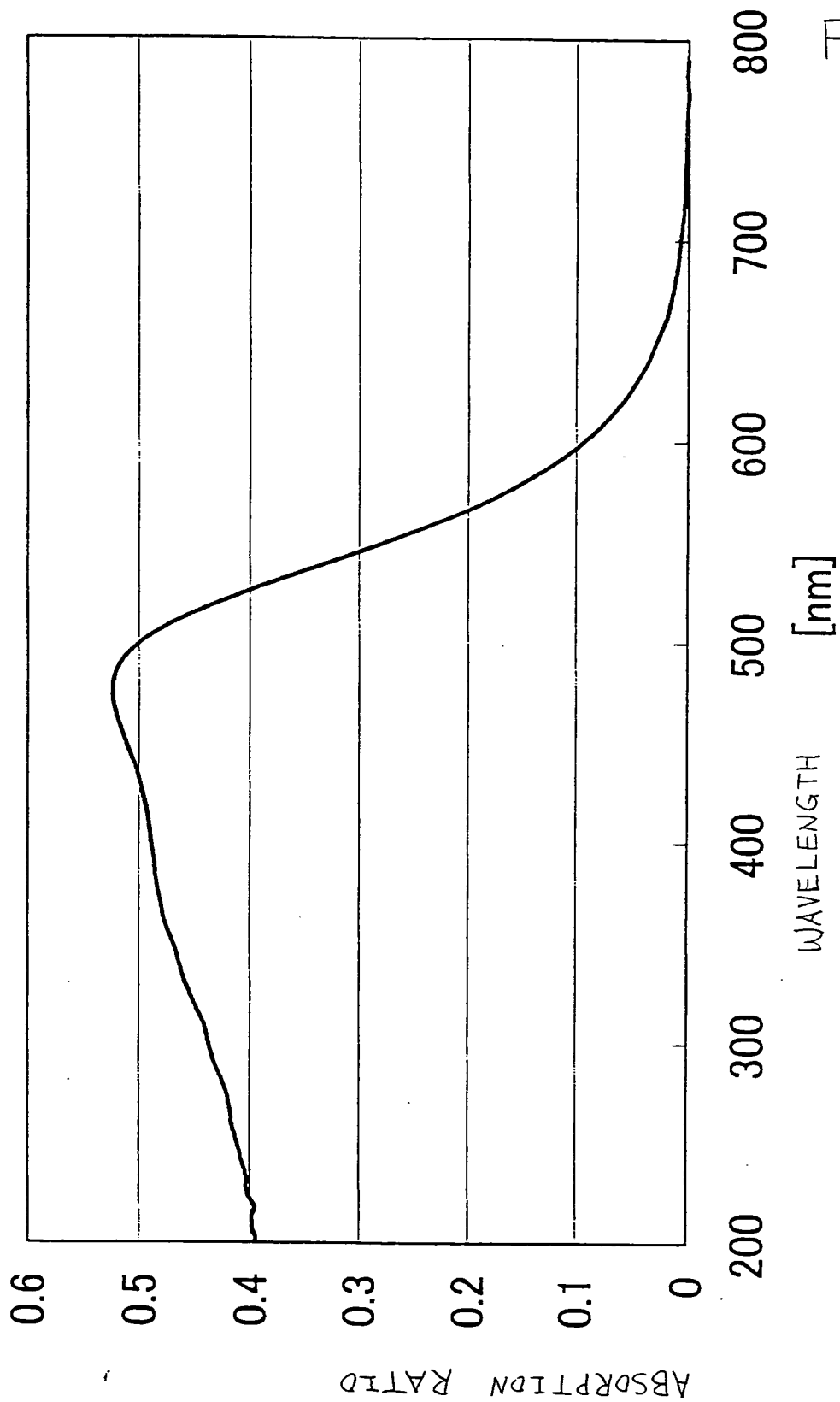


Fig. 34